Zener Diode

DZ2422000L

## **Panasonic**

#### DZ2422000L

#### Silicon epitaxial planar type

For constant voltage / For surge absorption circuit Capability of withstanding a high surge type DZ2W220 in Power type package

#### ■ Features

- · Excellent rising characteristics of zener current Iz
- · Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: CG

#### ■ Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

| Parameter                             | Symbol | Rating      | Unit |
|---------------------------------------|--------|-------------|------|
| Repetitive peak forward current       | IFRM   | 500         | mA   |
| Forward current                       | IF     | 400         | mA   |
| Total power dissipation *1            | PT     | 2           | W    |
| Non-repetitive reverse power surge *2 | PZSM   | 100         | W    |
| Electrostatic discharge *3            | ESD    | ±30         | kV   |
| Junction temperature                  | Tj     | 150         | °C   |
| Operating ambient temperature         | Topr   | -40 to +85  | °C   |
| Storage temperature                   | Tstg   | -55 to +150 | °C   |

Note: \*1 Mounted on ceramics print circuit board.

Board size: 50 mm × 50 mm Board thickness: 0.8 mm Soldering size: 2 mm × 2 mm

- \*2 t = 0.1ms
- \*3 Test method:IEC61000\_4\_2(C = 150 pF,R = 330  $\Omega$ , Contact discharge:10 times)

#### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

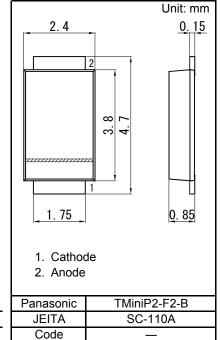
| Parameter                                   | Symbol | Conditions  | Min   | Тур   | Max   | Unit  |
|---|--------|-------------|-------|-------|-------|-------|
| Forward voltage                             | VF     | IF = 200 mA |       |       | 1.2   | V     |
| Zener voltage *1, *2                        | VZ     | IZ = 10 mA  | 20.90 | 22.00 | 23.10 | V     |
| Zener operating resistance                  | RZ     | IZ = 10 mA  |       |       | 30    | Ω     |
| Reverse current                             | IR     | VR = 16.0 V |       |       | 10    | μA    |
| Temperature coefficient of zener voltage *3 | SZ     | IZ = 10 mA  |       | 21.8  |       | mV/°C |

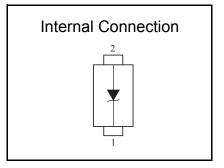
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
  - 2. Absolute frequency of input and output is 5 MHz.
  - \*1 The temperature must be controlled 25°C for VZ mesurement.
     VZ value measured at other temperature must be adjusted to VZ (25°C)
    - \*2 VZ guaranted 20 ms after current flow.
    - \*3 Tj = 25°C to 150°C

: 2013-05-13

Established: 2011-09-09

Revised



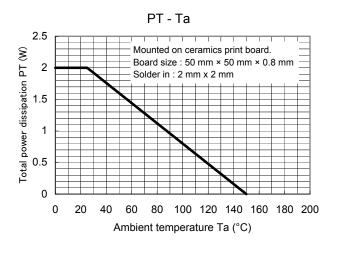


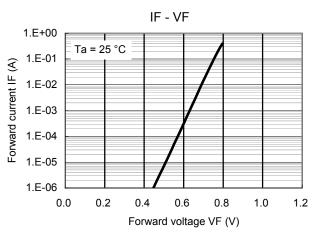
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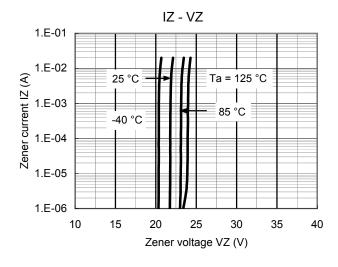
Zener Diode

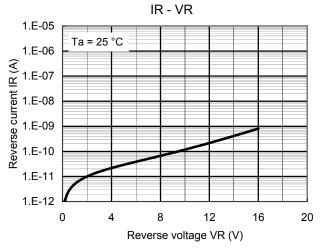
### DZ2422000L

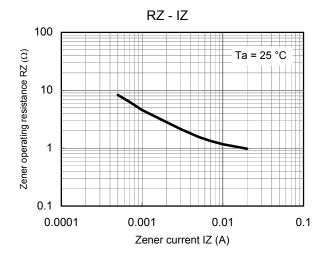
### Technical Data (reference)

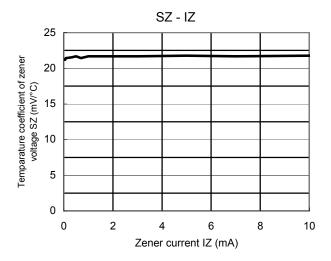










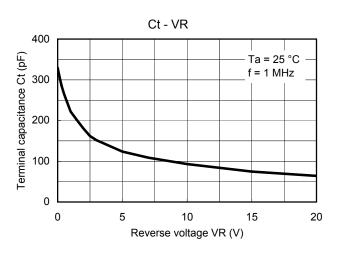


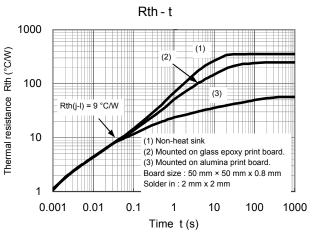
Established: 2011-09-09 Revised: 2013-05-13

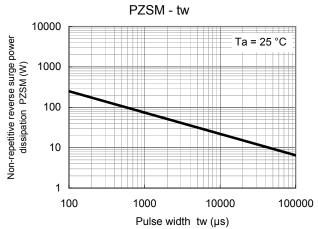
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### Technical Data (reference)







Established: 2011-09-09 Revised: 2013-05-13

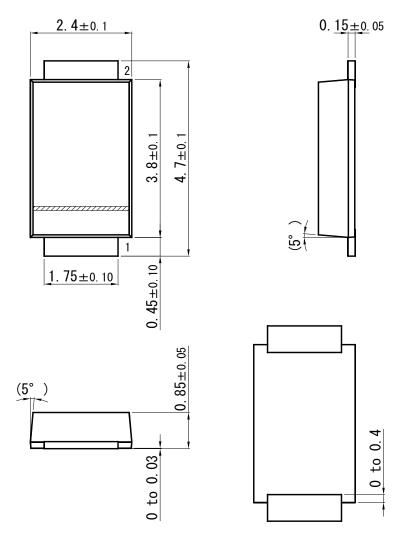
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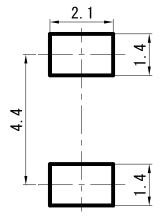
## TMiniP2-F2-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)

Established: 2011-09-09 Revised: 2013-05-13



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